

SPECIFICATION

PART NO. : LT632G-H201

2.9mm ROUND LED LAMP WITH HOLDER



Approved by

Checked by

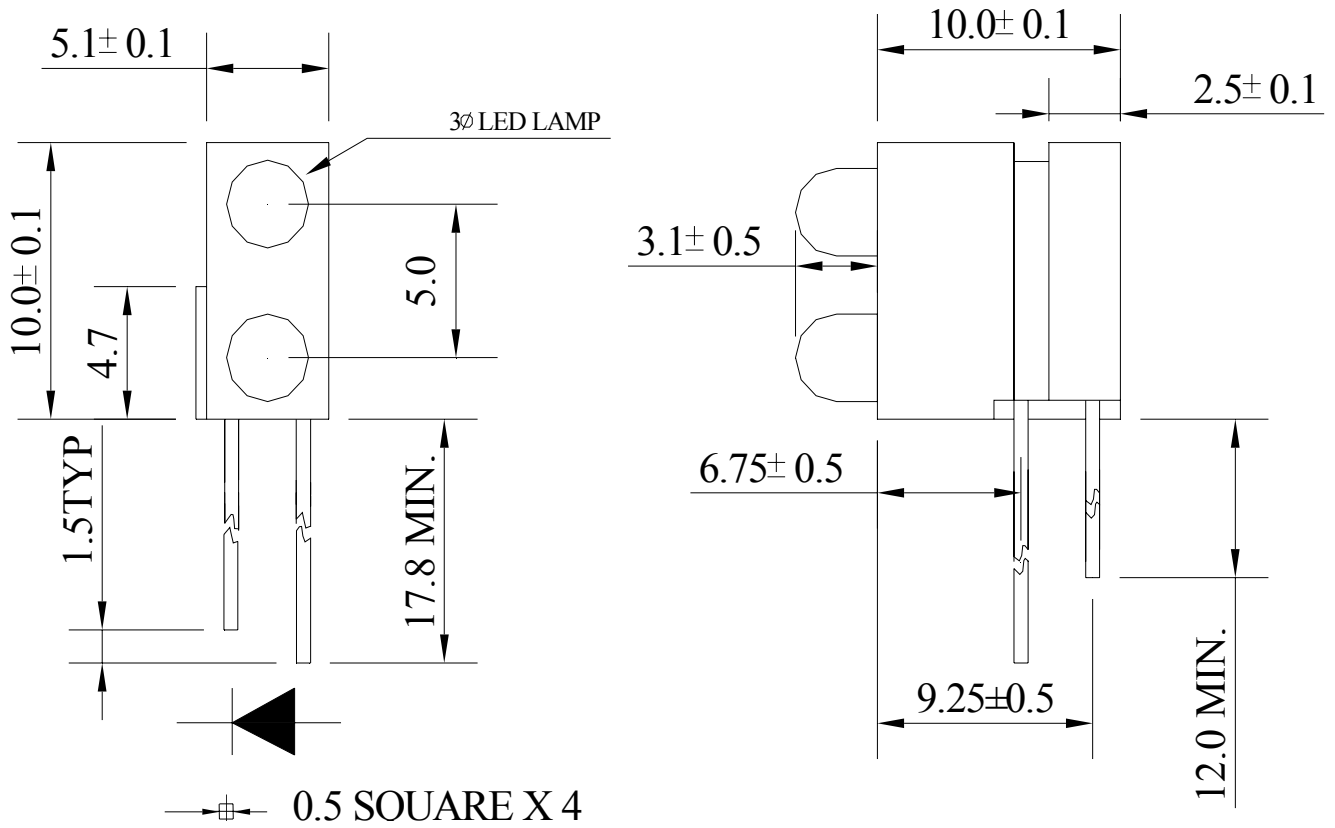
Prepared by

SAN

Sunny

Angel

Package Dimensions



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ±0.25mm unless otherwise noted.
3. The color of holder: Black.

Description

Part No.	LED Chip		Description
	Material	Emitting Color	
LT632G-H201	GaP/GaP	Green	Green Diffused

LT632G-H2012.9mm ROUND LED
LAMP WITH HOLDER**Absolute Maximum Ratings at Ta=25 °C**

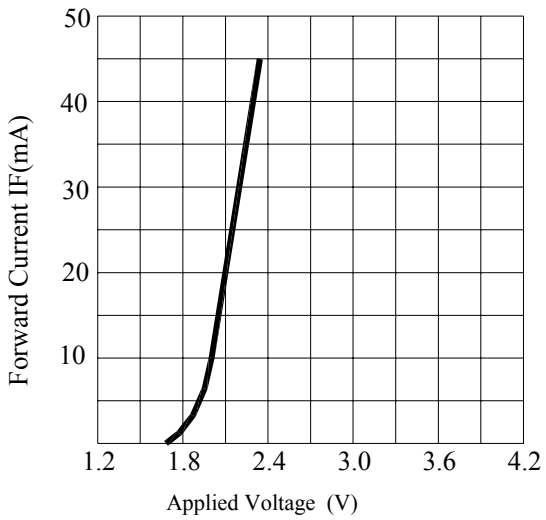
Parameter	Symbol	Rating	Unit
Power Dissipation	P _D	78	mW
Reverse Voltage	V _R	5	V
D.C. Forward Current	I _f	30	mA
Peak Current(1/10Duty duty,0.1ms Pulse Width.)	I _f (Peak)	100	mA
Operating Temperature Range	T _{opr.}	-25 to +85	°C
Storage Temperature Range	T _{stg.}	-40 to +100	°C

Electrical and Optical Characteristics:

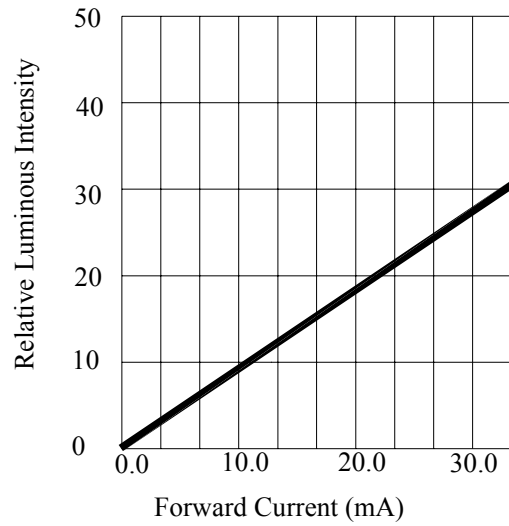
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _f =20mA	11.0	18.0		mcd
Forward Voltage	V _f	I _f =20mA		2.1	2.6	V
Peak Wavelength	λ _P	I _f =20mA		567		nm
Dominant Wavelength	λ _D	I _f =20mA		572		nm
Reverse Current	I _r	V _r =5V			100	μA
Viewing Angle	2θ 1/2	I _f =20mA		55		deg
Spectrum Line Halfwidth	Δλ	I _f =20mA		30		nm

NOTE:THE DATAS COME FROM THE SPEC. OF LT6321-41

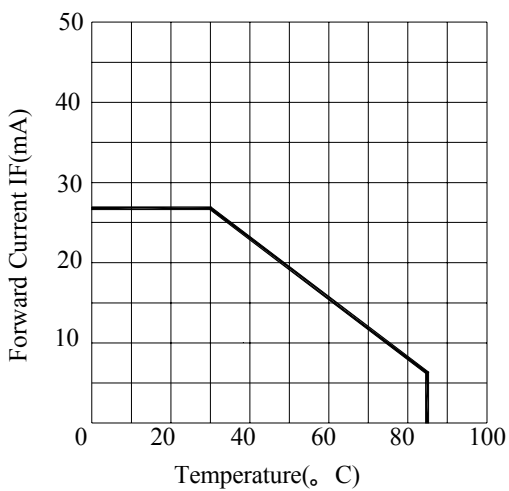
**Typical Electrical/Optical Characteristic Curves
(Lamp tested in 25°C Ambient Temperature)**



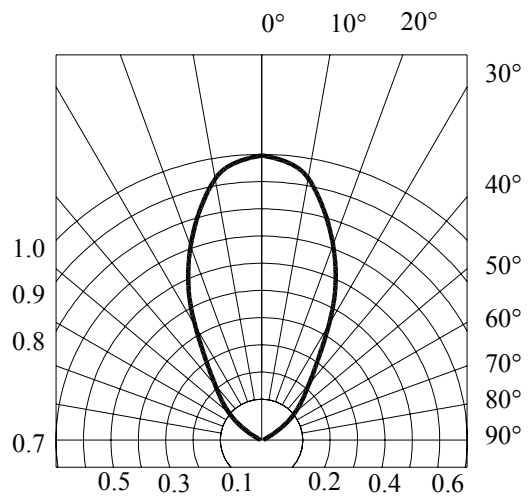
FORWARD CURRENT VS. APPLIED VOLTAGE



FORWARD CURRENT VS. LUMINOUS INTENSITY



FORWARD CURRENT VS. AMBIENT TEMPERATURE



RADIATION DIAGRAM

Precautions in Use:

Storage

Recommend storage environment

Temperature : 5 ~30

Soldering

Reflow Soldering

Recommend use of upper and lower heater type reflow furnace.

300°C Max for up to 5 seconds.

Pre-heat is 150°C Max for up to 2 minutes Max.

In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm.

Manual Iron Soldering (NOT RECOMMENDED)

Use SN60 solder of solder with silver content.

Use 25W soldering iron at 300°C Max for 5 seconds or less.

Must not touch top resin portion of lamp by heated soldering iron.

Cleaning

Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

Avoid using organic solvent.

Recommend ultrasonic method 300W Max.

Reflow Temp/Time:

